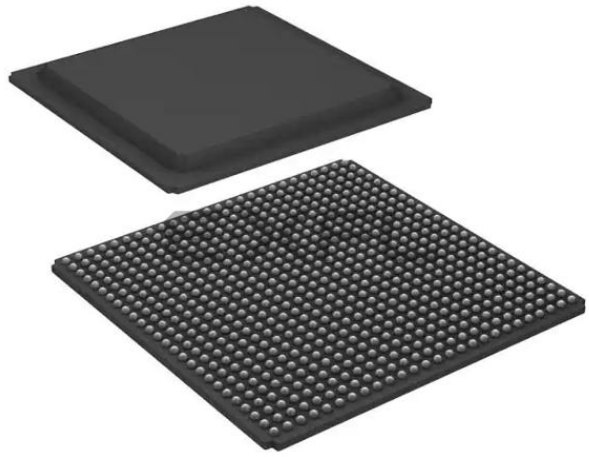
AMD Xilinx - XC2VP30-6FG676C Datasheet



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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	3424
Number of Logic Elements/Cells	30816
Total RAM Bits	2506752
Number of I/O	416
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	676-BGA
Supplier Device Package	676-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp30-6fg676c

CRC may adjust certain trailing bytes to generate the required running disparity at the end of the packet.

On the receiver side, the CRC logic verifies the received CRC value, supporting the same standards as above.

The CRC logic also supports a user mode, with a simple data packet stucture beginning and ending with user-defined SOP and EOP characters.

Loopback

In order to facilitate testing without having the need to either apply patterns or measure data at GHz rates, two programmable loop-back features are available.

One option, serial loopback, places the gigabit transceiver into a state where transmit data is directly fed back to the receiver. An important point to note is that the feedback path is at the output pads of the transmitter. This tests the entirety of the transmitter and receiver.

The second option, parallel loopback, checks the digital circuitry. When parallel loopback is enabled, the serial loopback path is disabled. However, the transmitter outputs remain active, and data can be transmitted. If TXINHIBIT is asserted, TXP is forced to 0 until TXINHIBIT is de-asserted.

Reset

The receiver and transmitter have their own synchronous reset inputs. The transmitter reset recenters the transmission FIFO, and resets all transmitter registers and the 8B/10B decoder. The receiver reset recenters the receiver elastic buffer, and resets all receiver registers and the 8B/10B encoder. Neither reset has any effect on the PLLs.

Power

All RocketIO transceivers in the FPGA, whether instantiated in the design or not, must be connected to power and ground. Unused transceivers can be powered by any 2.5V source, and passive filtering is not required.

Power Down

The Power Down module is controlled by the transceiver's POWERDOWN input pin. The Power Down pin on the FPGA package has no effect on the transceiver.

Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics

DS083 (v5.0) June 21, 2011 **Product Specification**

Virtex-II Pro[1] Electrical Characteristics

Virtex™-II Pro devices are provided in -7, -6, and -5 speed grades, with -7 having the highest performance.

Virtex-II Pro DC and AC characteristics are specified for both commercial and industrial grades. Except the operating temperature range or unless otherwise noted, all the DC and AC electrical parameters are the same for a particular speed grade (that is, the timing characteristics of a -6 speed grade industrial device are the same as for a -6 speed grade commercial device). However, only selected speed grades and/or devices might be available in the industrial range.

All supply voltage and junction temperature specifications are representative of worst-case conditions. The parameters included are common to popular designs and typical applications. Contact Xilinx for design considerations requiring more detailed information.

All specifications are subject to change without notice.

Virtex-II Pro DC Characteristics

Table 1: **Absolute Maximum Ratings**

Symbol	Description[1]		Virtex-II Pro X	Virtex-II Pro	Units
V_{CCINT}	Internal supply voltage relative to GND		–0.5 to 1.6		V
V_{CCAUX}	Auxiliary supply voltage relative to GND		–0.5 to 3.0		V
V_{CCO}	Output drivers supply voltage relative to GND		–0.5 to 3.75		V
V_{BATT}	Key memory battery backup supply		–0.5 to 4.05		V
V_{REF}	Input reference voltage		–0.3 to 3.75		V
V_{IN}	3.3V I/O input voltage relative to GND (user and dedicated I/Os)		–0.3 to 4.05[3]		V
	2.5V or below I/O input voltage relative to GND (user and dedicated I/Os)		–0.5 to V_{CCO} + 0.5		V
V_{TS}	Voltage applied to 3-state 3.3V output (user and dedicated I/Os)		–0.3 to 4.05[3]		V
	Voltage applied to 3-state 2.5V or below output (user and dedicated I/Os)		–0.5 to V_{CCO} + 0.5		V
AVCCAUXRX	Receive auxilliary supply voltage relative to GNDA (analog ground)		–0.5 to 2.0	–0.5 to 3.0	V
AVCCAUXTX	Transmit auxilliary supply voltage relative to GNDA (analog ground)		–0.5 to 3.0	–0.5 to 3.0	V
V_{TRX}	Terminal receive supply voltage relative to GND		–0.5 to 3.0	–0.5 to 3.0	V
V_{TTX}	Terminal transmit supply voltage relative to GND		–0.5 to 1.6	–0.5 to 3.0	V
T_{STG}	Storage temperature (ambient)		–65 to +150		°C
T_{SOL}	Maximum soldering temperature[2]	All regular FG/FF flip-chip packages	+220		°C
		Pb-free FGG256 wire-bond package	N/A	+260	°C
		Pb-free FGG456 and FGG676 wire-bond packages	N/A	+250	°C
T_J	Maximum junction temperature[2]		+125		°C

Notes:

1. Stresses beyond those listed under Absolute Maximum Ratings might cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those listed under Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time might affect device reliability.
2. For soldering guidelines and thermal considerations, see the **Device Packaging and Thermal Characteristics Guide** information on the Xilinx website.
3. 3.3V I/O Absolute Maximum limit applied to DC and AC signals. Refer to **XAPP659** for more details.

1. Unless otherwise noted, "Virtex-II Pro" refers to members of the Virtex-II Pro and/or Virtex-II Pro X families.

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Table 2: **Recommended Operating Conditions**

Symbol	Description	Grade	Virtex-II Pro X		Virtex-II Pro		Units
			Min	Max	Min	Max	
V_{CCINT}	Internal supply voltage relative to GND, T_J = 0 °C to +85°C	Comm.	1.425	1.575	1.425	1.575	V
	Internal supply voltage relative to GND, T_J = –40°C to +100°C	Indus.	1.425	1.575	1.425	1.575	V
V_{CCAUX}(1)	Auxiliary supply voltage relative to GND, T_J = 0 °C to +85°C	Comm.	2.375	2.625	2.375	2.625	V
	Auxiliary supply voltage relative to GND, T_J = –40°C to +100°C	Indus.	2.375	2.625	2.375	2.625	V
V_{CCO}(2,3)	Supply voltage relative to GND, T_J = 0 °C to +85°C	Comm.	1.2	3.45(5)	1.2	3.45(5)	V
	Supply voltage relative to GND, T_J = –40°C to +100°C	Indus.	1.2	3.45(5)	1.2	3.45(5)	V
V_{IN}	3.3V supply voltage relative to GND, T_J = 0 °C to +85°C	Comm.	GND – 0.2	3.45(5)	GND – 0.2	3.45(5)	V
	3.3V supply voltage relative to GND, T_J = –40°C to +100°C	Indus.	GND – 0.2	3.45(5)	GND – 0.2	3.45(5)	V
	2.5V and below supply voltage relative to GND, T_J = 0 °C to +85°C	Comm.	GND – 0.2	V_{CCO} + 0.2	GND – 0.2	V_{CCO} + 0.2	V
	2.5V and below supply voltage relative to GND, T_J = –40°C to +100°C	Indus.	GND – 0.2	V_{CCO} + 0.2	GND – 0.2	V_{CCO} + 0.2	V
V_{BATT}(4)	Battery voltage relative to GND, T_J = 0 °C to +85°C	Comm.	1.0	3.6	1.0	3.6	V
	Battery voltage relative to GND, T_J = –40°C to +100°C	Indus.	1.0	3.6	1.0	3.6	V
AVCCAUXRX(6)	Auxilliary receive supply voltage relative to GNDA	Comm.	1.425(7)	1.575(7)	2.375	2.625	V
		Indus.	1.425(7)	1.575(7)	2.375	2.625	V
AVCCAUXTX(6)	Auxilliary transmit supply voltage relative to GNDA	Comm.	2.375	2.625	2.375	2.625	V
		Indus.	2.375	2.625	2.375	2.625	V
V_{TRX}	Terminal receive supply voltage relative to GND	Comm.	0	2.625	1.6	2.625	V
		Indus.	0	2.625	1.6	2.625	V
V_{TTX}	Terminal transmit supply voltage relative to GND	Comm.	1.425	1.575	1.6	2.625	V
		Indus.	1.425	1.575	1.6	2.625	V

Notes:
1. Recommended maximum voltage droop for V_{CCAUX} is 10 mV/ms.
2. Configuration data is retained even if V_{CCO} drops to 0V.
3. For 3.3V I/O operation, refer to **XAPP659**, available on the Xilinx website at **www.xilinx.com**.
4. If battery is not used, connect V_{BATT} to GND or V_{CCAUX}.
5. For PCI and PCI-X, refer to **XAPP653**, available on the Xilinx website at **www.xilinx.com**.
6. **IMPORTANT!** The RocketIO transceivers have certain power guidelines that must be met, even if unused in the design. Please refer to the section entitled “Powering the RocketIO Transceivers” in the ***RocketIO Transceiver User Guide*** or ***RocketIO X Transceiver User Guide*** for more details.
7. For non-8B/10B-encoded data, the specification for AVCCAUXRX is 1.8V ±5% (1.71 – 1.89V).

RocketIO Switching Characteristics

Table 22: **RocketIO X Reference Clock Switching Characteristics**

			All Speed Grades			
Description	**Symbol**	**Conditions**	**Min**	**Typ**	**Max**	**Units**
Reference Clock frequency range(1)	F_{GCLK}		62.5		425	MHz
Reference Clock frequency tolerance	F_{GTOL}				±350	ppm
Reference Clock rise time	T_{RCLK}	20% – 80%		75		ps
Reference Clock fall time	T_{FCLK}	20% – 80%		75		ps
Reference Clock duty cycle	T_{DCREF}		45	50	55	%
Reference Clock total jitter, peak-peak	T_{GJTT}	3.125 Gb/s – 6.25 Gb/s			30	ps
		2.488 Gb/s – 3.125 Gb/s			40	ps
Clock recovery frequency acquisition time, from Power-up to High state of PMARXLOCK	T_{LOCK}			100		µs
Clock recovery phase acquisition time, from Data to High state of PMARXLOCK	T_{PHASE}			40	60	µs

Notes:
1. BREFCLK should be used for all serial bit rates up to the maximum shown.

Table 23: **RocketIO Reference Clock Switching Characteristics**

			All Speed Grades			
Description	**Symbol**	**Conditions**	**Min**	**Typ**	**Max**	**Units**
Reference Clock frequency range(1)	F_{GCLK}	Full rate operation	50		156.25	MHz
		Half rate operation(2) (2X oversampling)	60		100	MHz
Reference Clock frequency tolerance	F_{GTOL}				±100	ppm
Reference Clock rise time	T_{RCLK}	20% – 80%		600	1000	ps
Reference Clock fall time	T_{FCLK}	20% – 80%		600	1000	ps
Reference Clock duty cycle	T_{DCREF}		45	50	55	%
Reference Clock total jitter, peak-peak(3)	T_{GJTT}	2.501 Gb/s – 3.125 Gb/s			40	ps
		1.061 Gb/s – 2.5 Gb/s			50	ps
		< 1.06 Gb/s			120	ps
Clock recovery frequency acquisition time	T_{LOCK}				10	µs
Clock recovery phase acquisition time	T_{PHASE}			960		bits(4)

Notes:
1. BREFCLK/BREFCLK2 can be used for all serial bit rates up to the maximum shown. REFCLK/REFCLK2 can be used for serial bit rates up to 2.5 Gb/s (REFCLK = 125 MHz). All other parameters apply equally to REFCLK, REFCLK2, BREFCLK, and BREFCLK2 except as noted.
2. For serial rates under 1 Gb/s, the 3X (or greater) oversampling techniques described in **XAPP572** are required to meet the transmit jitter and receive jitter tolerance specifications defined in this data sheet.
3. Measured at the package pin. For reference clock frequencies equal to or above 125 MHz, BREFCLK/BREFCLK2 must be used.
4. 8B/10B-type bitstream.

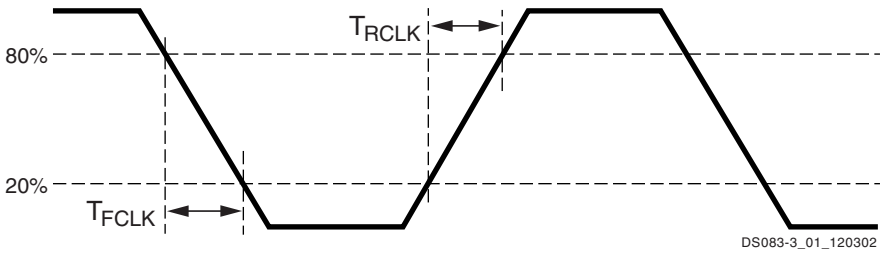


Figure 3: **Reference Clock Timing Parameters**

CLB Distributed RAM Switching Characteristics

Table 43: **CLB Distributed RAM Switching Characteristics**

Description	Symbol	Speed Grade			Units
		-7	-6	-5	
Sequential Delays					
Clock CLK to X/Y outputs (WE active) in 16 x 1 mode	$T_{SHCKO16}$	1.25	1.38	1.54	ns, max
Clock CLK to X/Y outputs (WE active) in 32 x 1 mode	$T_{SHCKO32}$	1.57	1.75	1.95	ns, max
Clock CLK to F5 output	$T_{SHCKOF5}$	1.52	1.68	1.88	ns, max
Setup and Hold Times Before/After Clock CLK					
BX/BY data inputs (DIN)	T_{DS}/T_{DH}	0.38/–0.07	0.41/–0.07	0.46/–0.08	ns, min
F/G address inputs	T_{AS}/T_{AH}	0.42/ 0.00	0.47/ 0.00	0.52/ 0.00	ns, min
SR input	T_{WES}/T_{WEH}	0.22/ 0.04	0.24/ 0.05	0.26/ 0.05	ns, min
Clock CLK					
Minimum Pulse Width, High	T_{WPH}	0.63	0.72	0.79	ns, min
Minimum Pulse Width, Low	T_{WPL}	0.63	0.72	0.79	ns, min
Minimum clock period to meet address write cycle time	T_{WC}	1.25	1.44	1.58	ns, min

Notes:
1. A Zero “0” Hold Time listing indicates no hold time or a negative hold time. Negative values cannot be guaranteed “best-case”, but if a “0” is listed, there is no positive hold time.

CLB Shift Register Switching Characteristics

Table 44: **CLB Shift Register Switching Characteristics**

Description	Symbol	Speed Grade			Units
		-7	-6	-5	
Sequential Delays					
Clock CLK to X/Y outputs	T_{REG}	2.78	3.12	3.49	ns, max
Clock CLK to X/Y outputs	T_{REG32}	3.10	3.49	3.90	ns, max
Clock CLK to XB output via MC15 LUT output	T_{REGXB}	2.84	3.18	3.55	ns, max
Clock CLK to YB output via MC15 LUT output	T_{REGYB}	2.55	2.88	3.21	ns, max
Clock CLK to Shiftout	T_{CKSH}	2.50	2.83	3.15	ns, max
Clock CLK to F5 output	T_{REGF5}	3.05	3.42	3.83	ns, max
Setup and Hold Times Before/After Clock CLK					
BX/BY data inputs (DIN)	T_{SRLDS}/T_{SRLDH}	0.70/–0.16	0.77/–0.18	0.98/–0.21	ns, min
SR input	T_{WSS}/T_{WSH}	0.27/ 0.01	0.34/ 0.01	0.47/ 0.01	ns, min
Clock CLK					
Minimum Pulse Width, High	T_{SRPH}	0.63	0.72	0.79	ns, min
Minimum Pulse Width, Low	T_{SRPL}	0.63	0.72	0.79	ns, min

Notes:
1. A Zero “0” Hold Time listing indicates no hold time or a negative hold time. Negative values cannot be guaranteed “best-case”, but if a “0” is listed, there is no positive hold time.

Table 5: **FG256/FGG256 — XC2VP2 and XC2VP4**

Bank	Pin Description	Pin Number
7	IO_L85N_7	G2
7	IO_L06P_7	G3
7	IO_L06N_7	G4
7	IO_L04P_7	F1
7	IO_L04N_7/VREF_7	F2
7	IO_L03P_7	F3
7	IO_L03N_7	F4
7	IO_L02P_7	F5
7	IO_L02N_7	E4
7	IO_L01P_7/VRN_7	E2
7	IO_L01N_7/VRP_7	E3
0	VCCO_0	F8
0	VCCO_0	F7
0	VCCO_0	E8
1	VCCO_1	F9
1	VCCO_1	F10
1	VCCO_1	E9
2	VCCO_2	H12
2	VCCO_2	H11
2	VCCO_2	G11
3	VCCO_3	K11
3	VCCO_3	J12
3	VCCO_3	J11
4	VCCO_4	M9
4	VCCO_4	L9
4	VCCO_4	L10
5	VCCO_5	M8
5	VCCO_5	L8
5	VCCO_5	L7
6	VCCO_6	K6
6	VCCO_6	J6
6	VCCO_6	J5
7	VCCO_7	H6
7	VCCO_7	H5

Table 6: **FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
7	VCCO_7	K7			
7	VCCO_7	J7			
7	VCCO_7	H6			
7	VCCO_7	G6			
N/A	CCLK	W20			
N/A	PROG_B	B1			
N/A	DONE	Y18			
N/A	M0	Y4			
N/A	M1	W3			
N/A	M2	Y5			
N/A	TCK	B22			
N/A	TDI	D3			
N/A	TDO	D20			
N/A	TMS	A21			
N/A	PWRDWN_B	Y19			
N/A	HSWAP_EN	A2			
N/A	RSVD	C18			
N/A	VBATT	C19			
N/A	DXP	C4			
N/A	DXN	C5			
N/A	AVCCAUXTX4	B4	NC	NC	
N/A	VTTXPAD4	B3	NC	NC	
N/A	TXNPAD4	A3	NC	NC	
N/A	TXPPAD4	A4	NC	NC	
N/A	GNDA4	C6	NC	NC	
N/A	RXPPAD4	A5	NC	NC	
N/A	RXNPAD4	A6	NC	NC	
N/A	VTRXPAD4	B5	NC	NC	
N/A	AVCCAUXRX4	B6	NC	NC	
N/A	AVCCAUXTX6	B8			
N/A	VTTXPAD6	B7			
N/A	TXNPAD6	A7			
N/A	TXPPAD6	A8			
N/A	GNDA6	C9			
N/A	RXPPAD6	A9			
N/A	RXNPAD6	A10			

Table 7: **FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
0	IO_L55N_0	G12			
0	IO_L55P_0	F12			
0	IO_L57N_0	E12			
0	IO_L57P_0/VREF_0	F13			
0	IO_L67N_0	D12			
0	IO_L67P_0	C12			
0	IO_L69N_0	J13			
0	IO_L69P_0/VREF_0	H13			
0	IO_L74N_0/GCLK7P	E13			
0	IO_L74P_0/GCLK6S	D13			
0	IO_L75N_0/GCLK5P	C13			
0	IO_L75P_0/GCLK4S	B13			
1	IO_L75N_1/GCLK3P	B14			
1	IO_L75P_1/GCLK2S	C14			
1	IO_L74N_1/GCLK1P	D14			
1	IO_L74P_1/GCLK0S	E14			
1	IO_L69N_1/VREF_1	H14			
1	IO_L69P_1	J14			
1	IO_L67N_1	C15			
1	IO_L67P_1	D15			
1	IO_L57N_1/VREF_1	F14			
1	IO_L57P_1	E15			
1	IO_L55N_1	F15			
1	IO_L55P_1	G15			
1	IO_L54N_1	H15			
1	IO_L54P_1	J15			
1	IO_L53_1/No_Pair	F16			
1	IO_L50_1/No_Pair	G16			
1	IO_L49N_1	C17			
1	IO_L49P_1	D17			
1	IO_L48N_1	E16			
1	IO_L48P_1	E17			
1	IO_L46N_1	H16			
1	IO_L46P_1	H17			

Table 7: **FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
7	IO_L52P_7	M7			
7	IO_L52N_7/VREF_7	L7			
7	IO_L50P_7	K1			
7	IO_L50N_7	K2			
7	IO_L49P_7	L3			
7	IO_L49N_7	K3			
7	IO_L48P_7	K4			
7	IO_L48N_7	K5			
7	IO_L46P_7	L8			
7	IO_L46N_7/VREF_7	K8			
7	IO_L44P_7	J1			
7	IO_L44N_7	J2			
7	IO_L43P_7	J3			
7	IO_L43N_7	J4			
7	IO_L42P_7	J5			
7	IO_L42N_7	J6			
7	IO_L40P_7	J7			
7	IO_L40N_7/VREF_7	J8			
7	IO_L38P_7	H1			
7	IO_L38N_7	H2			
7	IO_L37P_7	H6			
7	IO_L37N_7	H7			
7	IO_L36P_7	G1			
7	IO_L36N_7	G2			
7	IO_L34P_7	G3			
7	IO_L34N_7/VREF_7	G4			
7	IO_L32P_7	H5			
7	IO_L32N_7	G5			
7	IO_L31P_7	F1			
7	IO_L31N_7	F2			
7	IO_L24P_7	F3	NC		
7	IO_L24N_7	F4	NC		
7	IO_L06P_7	G6			
7	IO_L06N_7	F6			
7	IO_L04P_7	E1			

Table 7: **FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
N/A	GND	R15			
N/A	GND	R16			
N/A	GND	R24			
N/A	GND	T11			
N/A	GND	T12			
N/A	GND	T13			
N/A	GND	T14			
N/A	GND	T15			
N/A	GND	T16			
N/A	GND	U6			
N/A	GND	U21			
N/A	GND	W4			
N/A	GND	W23			
N/A	GND	AA10			
N/A	GND	AA17			
N/A	GND	AC4			
N/A	GND	AC8			
N/A	GND	AC19			
N/A	GND	AC23			
N/A	GND	AD3			
N/A	GND	AD24			
N/A	GND	AE2			
N/A	GND	AE25			
N/A	GND	AF1			
N/A	GND	AF26			

Notes:
1. See Table 4 for an explanation of the signals available on this pin.

Table 8: **FF672 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
1	IO_L06N_1	E9			
1	IO_L06P_1	E8			
1	IO_L05_1/No_Pair	F8			
1	IO_L03N_1/VREF_1	D7			
1	IO_L03P_1	E7			
1	IO_L02N_1	C6			
1	IO_L02P_1	D6			
1	IO_L01N_1/VRP_1	A3			
1	IO_L01P_1/VRN_1	B3			
2	IO_L01N_2/VRP_2	C4			
2	IO_L01P_2/VRN_2	D3			
2	IO_L02N_2	A2			
2	IO_L02P_2	B1			
2	IO_L03N_2	C2			
2	IO_L03P_2	C1			
2	IO_L04N_2/VREF_2	D2			
2	IO_L04P_2	D1			
2	IO_L05N_2	E4			
2	IO_L05P_2	E3			
2	IO_L06N_2	E2			
2	IO_L06P_2	E1			
2	IO_L40N_2/VREF_2	F5	NC	NC	NC
2	IO_L40P_2	F4	NC	NC	NC
2	IO_L42N_2	F3	NC	NC	NC
2	IO_L42P_2	F2	NC	NC	NC
2	IO_L43N_2	G6	NC		
2	IO_L43P_2	G5	NC		
2	IO_L44N_2	G4	NC		
2	IO_L44P_2	G3	NC		
2	IO_L45N_2	F1	NC		
2	IO_L45P_2	G1	NC		
2	IO_L46N_2/VREF_2	H6	NC		
2	IO_L46P_2	H5	NC		
2	IO_L47N_2	H4	NC		
2	IO_L47P_2	H3	NC		
2	IO_L48N_2	H2	NC		

Table 8: **FF672 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
5	IO_L74P_5/GCLK4P	AB14			
5	IO_L73N_5	AA14			
5	IO_L73P_5	Y14			
5	IO_L69N_5/VREF_5	W14			
5	IO_L69P_5	W15			
5	IO_L68N_5	AD15			
5	IO_L68P_5	AC15			
5	IO_L67N_5	AB15			
5	IO_L67P_5	AA15			
5	IO_L45N_5/VREF_5	AC16	NC	NC	
5	IO_L45P_5	AB16	NC	NC	
5	IO_L44N_5	Y15	NC	NC	
5	IO_L44P_5	Y16	NC	NC	
5	IO_L43N_5	AC17	NC	NC	
5	IO_L43P_5	AB17	NC	NC	
5	IO_L39N_5	AA16	NC	NC	
5	IO_L39P_5	AA17	NC	NC	
5	IO_L38N_5	W16	NC	NC	
5	IO_L38P_5	Y17	NC	NC	
5	IO_L37N_5	AD18	NC	NC	
5	IO_L37P_5	AC18	NC	NC	
5	IO_L09N_5/VREF_5	AA18			
5	IO_L09P_5	Y18			
5	IO_L08N_5	AF19			
5	IO_L08P_5	AE19			
5	IO_L07N_5/VREF_5	AD19			
5	IO_L07P_5	AC19			
5	IO_L06N_5/VRP_5	AB18			
5	IO_L06P_5/VRN_5	AB19			
5	IO_L05_5/No_Pair	Y19			
5	IO_L03N_5/D4	AA19			
5	IO_L03P_5/D5	AA20			
5	IO_L02N_5/D6	AC20			
5	IO_L02P_5/D7	AB20			
5	IO_L01N_5/RDWR_B	AD21			
5	IO_L01P_5/CS_B	AC21			

Table 8: **FF672 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
N/A	AVCCAUXRX19	AE15			
N/A	VTRXPAD19	AE16			
N/A	RXNPAD19	AF15			
N/A	RXPPAD19	AF16			
N/A	GNDA19	AD16			
N/A	TXPPAD19	AF17			
N/A	TXNPAD19	AF18			
N/A	VTTXPAD19	AE18			
N/A	AVCCAUXTX19	AE17			
N/A	AVCCAUXRX21	AE20	NC	NC	
N/A	VTRXPAD21	AE21	NC	NC	
N/A	RXNPAD21	AF20	NC	NC	
N/A	RXPPAD21	AF21	NC	NC	
N/A	GNDA21	AD22	NC	NC	
N/A	TXPPAD21	AF22	NC	NC	
N/A	TXNPAD21	AF23	NC	NC	
N/A	VTTXPAD21	AE23	NC	NC	
N/A	AVCCAUXTX21	AE22	NC	NC	
N/A	VCCINT	H8			
N/A	VCCINT	J9			
N/A	VCCINT	K9			
N/A	VCCINT	U9			
N/A	VCCINT	V9			
N/A	VCCINT	W8			
N/A	VCCINT	H19			
N/A	VCCINT	J10			
N/A	VCCINT	J17			
N/A	VCCINT	J18			
N/A	VCCINT	K11			
N/A	VCCINT	K16			
N/A	VCCINT	K18			
N/A	VCCINT	L10			
N/A	VCCINT	L17			
N/A	VCCINT	T10			
N/A	VCCINT	T17			
N/A	VCCINT	U11			

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
6	IO_L86P_6		T23			
6	IO_L86N_6		T24			
6	IO_L87P_6		U28			
6	IO_L87N_6/VREF_6		U29			
6	IO_L88P_6		T27			
6	IO_L88N_6		T28			
6	IO_L89P_6		T25			
6	IO_L89N_6		T26			
6	IO_L90P_6		V30			
6	IO_L90N_6		U30			
7	IO_L90P_7		R28			
7	IO_L90N_7		R27			
7	IO_L89P_7		R26			
7	IO_L89N_7		R25			
7	IO_L88P_7		T29			
7	IO_L88N_7/VREF_7		R29			
7	IO_L87P_7		P27			
7	IO_L87N_7		P26			
7	IO_L86P_7		R24			
7	IO_L86N_7		R23			
7	IO_L85P_7		P29			
7	IO_L85N_7		P28			
7	IO_L60P_7		N28			
7	IO_L60N_7		N27			
7	IO_L59P_7		P24			
7	IO_L59N_7		P23			
7	IO_L58P_7		P30			
7	IO_L58N_7/VREF_7		N30			
7	IO_L57P_7		M28			
7	IO_L57N_7		M27			
7	IO_L56P_7		R22			
7	IO_L56N_7		P22			
7	IO_L55P_7		N29			
7	IO_L55N_7		M29			
7	IO_L54P_7		L27			

Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
2	IO_L21P_2	E6		
2	IO_L22N_2/VREF_2	F7		
2	IO_L22P_2	F8		
2	IO_L23N_2	M10		
2	IO_L23P_2	L10		
2	IO_L24N_2	G5		
2	IO_L24P_2	F5		
2	IO_L25N_2	F3		
2	IO_L25P_2	F4		
2	IO_L26N_2	M8		
2	IO_L26P_2	M9		
2	IO_L27N_2	F1		
2	IO_L27P_2	F2		
2	IO_L28N_2/VREF_2	G6		
2	IO_L28P_2	G7		
2	IO_L29N_2	M7		
2	IO_L29P_2	N8		
2	IO_L30N_2	G3		
2	IO_L30P_2	H4		
2	IO_L31N_2	G1		
2	IO_L31P_2	G2		
2	IO_L32N_2	N10		
2	IO_L32P_2	N11		
2	IO_L33N_2	H5		
2	IO_L33P_2	H6		
2	IO_L34N_2/VREF_2	H2		
2	IO_L34P_2	H3		
2	IO_L35N_2	N6		
2	IO_L35P_2	N7		
2	IO_L36N_2	K4		
2	IO_L36P_2	J4		
2	IO_L37N_2	J2		
2	IO_L37P_2	J3		
2	IO_L38N_2	P10		
2	IO_L38P_2	P11		
2	IO_L39N_2	K5		
2	IO_L39P_2	K6		
2	IO_L40N_2/VREF_2	L3		

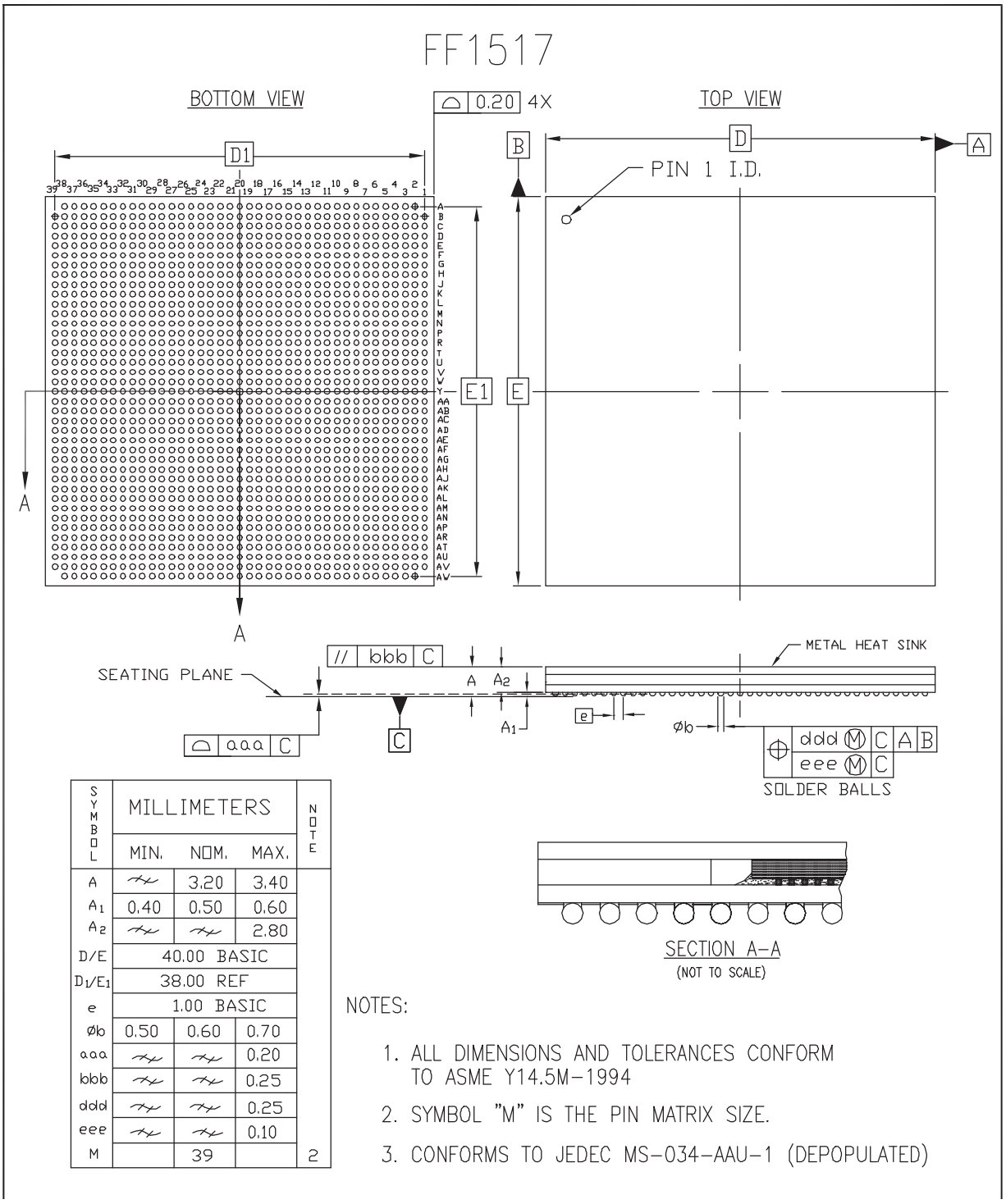
Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
6	IO_L44N_6	AA28		
6	IO_L45P_6	AC31		
6	IO_L45N_6/VREF_6	AC32		
6	IO_L46P_6	AC29		
6	IO_L46N_6	AC30		
6	IO_L47P_6	AA24		
6	IO_L47N_6	AA25		
6	IO_L48P_6	AB32		
6	IO_L48N_6	AB33		
6	IO_L49P_6	AB28		
6	IO_L49N_6	AB29		
6	IO_L50P_6	AA26		
6	IO_L50N_6	Y26		
6	IO_L51P_6	AA33		
6	IO_L51N_6/VREF_6	AA34		
6	IO_L52P_6	AB31		
6	IO_L52N_6	AA31		
6	IO_L53P_6	Y24		
6	IO_L53N_6	Y25		
6	IO_L54P_6	AA29		
6	IO_L54N_6	AA30		
6	IO_L55P_6	Y33		
6	IO_L55N_6	Y34		
6	IO_L56P_6	Y28		
6	IO_L56N_6	W27		
6	IO_L57P_6	AA32		
6	IO_L57N_6/VREF_6	Y32		
6	IO_L58P_6	Y29		
6	IO_L58N_6	Y30		
6	IO_L59P_6	W24		
6	IO_L59N_6	W25		
6	IO_L60P_6	W31		
6	IO_L60N_6	W32		
6	IO_L85P_6	W28		
6	IO_L85N_6	W29		
6	IO_L86P_6	V26		
6	IO_L86N_6	V27		
6	IO_L87P_6	W33		

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
2	IO_L49N_2	U5		
2	IO_L49P_2	U6		
2	IO_L50N_2	U13		
2	IO_L50P_2	V13		
2	IO_L51N_2	U4		
2	IO_L51P_2	T4		
2	IO_L52N_2/VREF_2	U1		
2	IO_L52P_2	U2		
2	IO_L53N_2	V9		
2	IO_L53P_2	V10		
2	IO_L54N_2	V7		
2	IO_L54P_2	V8		
2	IO_L55N_2	V5		
2	IO_L55P_2	V6		
2	IO_L56N_2	V11		
2	IO_L56P_2	V12		
2	IO_L57N_2	V3		
2	IO_L57P_2	V4		
2	IO_L58N_2/VREF_2	V1		
2	IO_L58P_2	V2		
2	IO_L59N_2	W10		
2	IO_L59P_2	W11		
2	IO_L60N_2	W7		
2	IO_L60P_2	W8		
2	IO_L85N_2	W5		
2	IO_L85P_2	W6		
2	IO_L86N_2	W12		
2	IO_L86P_2	W13		
2	IO_L87N_2	W3		
2	IO_L87P_2	W4		
2	IO_L88N_2/VREF_2	Y7		
2	IO_L88P_2	Y8		
2	IO_L89N_2	W9		
2	IO_L89P_2	Y9		
2	IO_L90N_2	Y3		
2	IO_L90P_2	Y4		
3	IO_L90N_3	AA7		

FF1517 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch)



SYMBOL	MILLIMETERS MIN.	NOM.	MAX.	NOTE
A		3.20	3.40	
A_1	0.40	0.50	0.60	
A_2			2.80	
D/E	40.00 BASIC			
D_1/E_1	38.00 REF			
e	1.00 BASIC			
øb	0.50	0.60	0.70	
aaa			0.20	
bbb			0.25	
ddd			0.25	
eee			0.10	
M		39		2

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994
2. SYMBOL "M" IS THE PIN MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAU-1 (DEPOPULATED)

Figure 8: **FF1517 Flip-Chip Fine-Pitch BGA Package Specifications**

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
5	IO_L66P_5	BA23	
5	IO_L65N_5	AL23	
5	IO_L65P_5	AL22	
5	IO_L64N_5	AT23	
5	IO_L64P_5	AU23	
5	IO_L60N_5	BA24	
5	IO_L60P_5	BB24	
5	IO_L59N_5	AN24	
5	IO_L59P_5	AP24	
5	IO_L58N_5	AW24	
5	IO_L58P_5	AW23	
5	IO_L57N_5/VREF_5	AU24	
5	IO_L57P_5	AV24	
5	IO_L56N_5	AN25	
5	IO_L56P_5	AP25	
5	IO_L55N_5	AR24	
5	IO_L55P_5	AR23	
5	IO_L54N_5	BA25	
5	IO_L54P_5	BB25	
5	IO_L53_5/No_Pair	AM25	
5	IO_L50_5/No_Pair	AM24	
5	IO_L49N_5	AY25	
5	IO_L49P_5	AY24	
5	IO_L48N_5	AU25	
5	IO_L48P_5	AV25	
5	IO_L47N_5	AM26	
5	IO_L47P_5	AN26	
5	IO_L46N_5	AT25	
5	IO_L46P_5	AT24	
5	IO_L18N_5/VREF_5	AY26	NC
5	IO_L18P_5	BA26	NC
5	IO_L16N_5	AT26	NC
5	IO_L16P_5	AU26	NC
5	IO_L12N_5	AL26	NC
5	IO_L12P_5	AL25	NC
5	IO_L11N_5	BA27	NC
5	IO_L11P_5	BB27	NC

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
N/A	GND	AC25	
N/A	GND	AB25	
N/A	GND	AA25	
N/A	GND	Y25	
N/A	GND	W25	
N/A	GND	V25	
N/A	GND	U25	
N/A	GND	AL24	
N/A	GND	AF24	
N/A	GND	AE24	
N/A	GND	AD24	
N/A	GND	AC24	
N/A	GND	AB24	
N/A	GND	AA24	
N/A	GND	Y24	
N/A	GND	W24	
N/A	GND	V24	
N/A	GND	U24	
N/A	GND	M24	
N/A	GND	BB23	
N/A	GND	AV23	
N/A	GND	AP23	
N/A	GND	AF23	
N/A	GND	AE23	
N/A	GND	AD23	
N/A	GND	AC23	
N/A	GND	AB23	
N/A	GND	AA23	
N/A	GND	Y23	
N/A	GND	W23	
N/A	GND	V23	
N/A	GND	U23	
N/A	GND	J23	
N/A	GND	E23	
N/A	GND	A23	
N/A	GND	AF22	
N/A	GND	AE22	